

**FILM-SHAPED ADHESIVE, ADHESIVE SHEET,
SEMICONDUCTOR DEVICE, AND PRODUCTION METHOD
FOR SEMICONDUCTOR DEVICE**

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ABSTRACT

Disclosed is a film-shaped adhesive for adhering a semiconductor element to a support member for mounting the semiconductor element. The film-shaped adhesive contains a heat-curable resin, a curing agent, an acrylic rubber, and an inorganic filler, the content of the inorganic filler is 0.5 to 10 parts by mass with respect to 100 parts by mass of the total mass of the heat-curable resin, the curing agent, the acrylic rubber, and the inorganic filler, and the thickness of the film-shaped adhesive is 15 μm or less.

15 Figure 1